

## Fall-2020 UM-SJTU JI Ve311 Lab #4

Instructor: Dr. Chang-Ching Tu

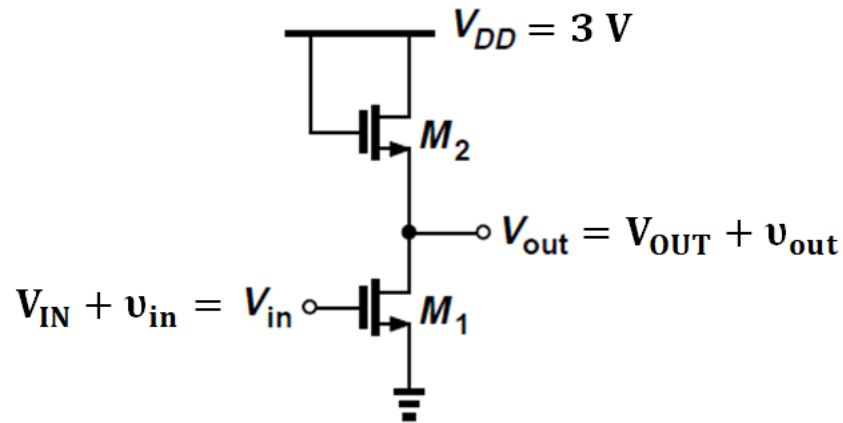
Due: 11:59 am, December 11, 2020 (Friday)

Note:

- (1) Please use A4 size papers.
  - (2) The lab report should be submitted online individually.
  - (3) Use Proteus 8.10 for simulation before the lab session. In the Proteus library, you should be able to find all the components used in the schematics.
- The lab report must include both the simulation and measurement results.**

### 1. [Common-Source with NMOS Diode-Connected Load]

- (a) [20%] Design and build a common-source with diode-connected load amplifier using NMOS (**VN0104**). Plot  $V_{OUT}$  vs  $V_{IN}$ . What is the voltage gain  $A_v$ ? (*Hint: Perform DC sweep of  $V_{IN}$  from 0 V to 3 V to find out a  $V_{IN}$  at which both transistors are in the saturation region. The voltage gain is the slope at the  $V_{IN}$ .*)  
**Caution: the transistors could become very hot with high drain current. Don't touch with bare hands before they fully cool down.**
- (b) [15%] Following (a), now put **two common-source NMOS in parallel**. Plot  $V_{OUT}$  vs  $V_{IN}$ . At the  $V_{IN}$  chosen in (a), does the voltage gain  $A_v$  double? Briefly explain the reason. (*Note: Make sure all NMOS remain in the saturation region.*)
- (c) [15%] Following (b), for  $V_{in} = V_{IN} + 0.01\sin(2\pi 10^2 \cdot \text{time})$ , plot  $V_{out} = V_{OUT} + v_{out}$  vs time. Confirm that the amplitude of  $v_{out}$  is close to  $0.01 \times A_v$ .

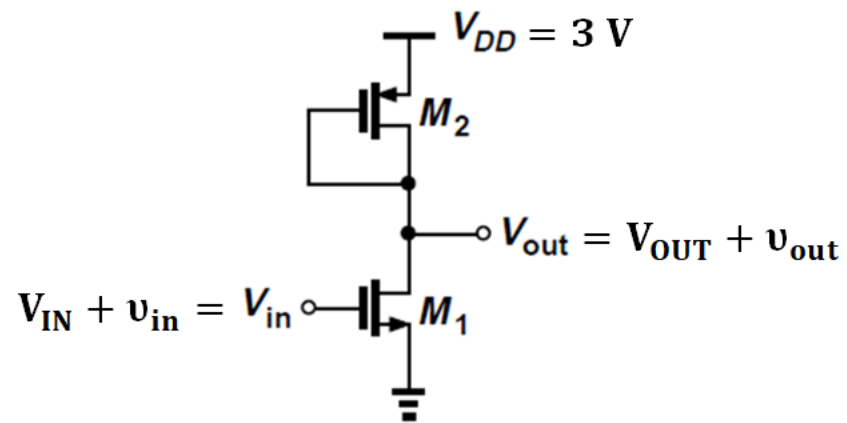


2. [Common-Source with PMOS Diode-Connected Load]

- (d) [20%] Design and build a common-source with diode-connected load amplifier using NMOS (**VN0104**) and PMOS (**VP0104**). Plot  $V_{OUT}$  vs  $V_{IN}$ . What is the voltage gain  $A_v$ ? (*Hint: Perform DC sweep of  $V_{IN}$  from 0 V to 3 V to find out a  $V_{IN}$  at which both transistors are in the saturation region. The voltage gain is the slope at the  $V_{IN}$ .*)

**Caution: the transistors could become very hot with high drain current. Don't touch with bare hands before they fully cool down.**

- (a) [15%] Following (a), now put **two PMOS diode-connected loads in parallel**. Plot  $V_{OUT}$  vs  $V_{IN}$ . At the  $V_{IN}$  chosen in (a), how does the voltage gain  $A_v$  change? Briefly explain the reason. (*Note: Make sure all NMOS and PMOS remain in the saturation region.*)
- (b) [15%] Following (b), for  $V_{in} = V_{IN} + 0.01\sin(2\pi 10^2 \cdot \text{time})$ , plot  $V_{out} = V_{OUT} + v_{out}$  vs time. Confirm that the amplitude of  $v_{out}$  is close to  $0.01 \times A_v$ .





## N-Channel Enhancement-Mode Vertical DMOS FET

### Features

- ▶ Free from secondary breakdown
- ▶ Low power drive requirement
- ▶ Ease of paralleling
- ▶ Low  $C_{iss}$  and fast switching speeds
- ▶ Excellent thermal stability
- ▶ Integral source-drain diode
- ▶ High input impedance and high gain

### Applications

- ▶ Motor controls
- ▶ Converters
- ▶ Amplifiers
- ▶ Switches
- ▶ Power supply circuits
- ▶ Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

### General Description

This enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven, silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

### Ordering Information

Device	Package Option	Wafer / Die Options		
	TO-92	NW (Die in wafer form)	NJ (Die on adhesive tape)	ND (Die in wafer pack)
VN0104	VN0104N3-G	VN1504NW	VN1504NJ	VN1504ND

For packaged products, -G indicates package is RoHS compliant ('Green'). Devices in Wafer / Die form are RoHS compliant ('Green'). Refer to Die Specification VF15 for layout and dimensions.

### Product Summary

$BV_{DSS}/BV_{DGS}$ (V)	$R_{DS(ON)}$ (max) ( $\Omega$ )	$I_{D(ON)}$ (min) (A)
40	3.0	2.0

### Absolute Maximum Ratings

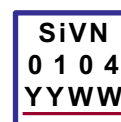
Parameter	Value
Drain-to-source voltage	$BV_{DSS}$
Drain-to-gate voltage	$BV_{DGS}$
Gate-to-source voltage	$\pm 20V$
Operating and storage temperature	$-55^{\circ}C$ to $+150^{\circ}C$

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

### Pin Configuration



### Product Marking



YY = Year Sealed  
WW = Week Sealed  
\_\_\_\_\_ = "Green" Packaging

Package may or may not include the following marks: Si or

TO-92 (N3)

## Thermal Characteristics

Package	$I_D$ (continuous) <sup>†</sup> (mA)	$I_D$ (pulsed) (A)	Power Dissipation @ $T_c = 25^\circ\text{C}$ (W)	$\theta_{jc}$ ( $^\circ\text{C/W}$ )	$\theta_{ja}$ ( $^\circ\text{C/W}$ )	$I_{DR}$ <sup>†</sup> (mA)	$I_{DRM}$ (A)
TO-92	350	2.0	1.0	125	170	350	2.0

### Notes:

<sup>†</sup>  $I_D$  (continuous) is limited by max rated  $T_J$ .

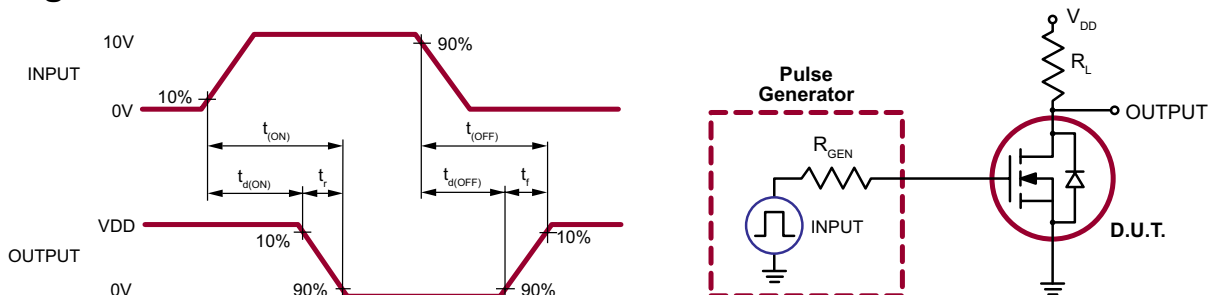
## Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter	Min	Typ	Max	Units	Conditions
$BV_{DSS}$	Drain-to-source breakdown voltage	40	-	-	V	$V_{GS} = 0V, I_D = 1.0mA$
$V_{GS(th)}$	Gate threshold voltage	0.8	-	2.4	V	$V_{GS} = V_{DS}, I_D = 1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-3.8	-5.5	mV/ $^\circ\text{C}$	$V_{GS} = V_{DS}, I_D = 1.0mA$
$I_{GSS}$	Gate body leakage	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
$I_{DSS}$	Zero gate voltage drain current	-	-	1.0	$\mu\text{A}$	$V_{GS} = 0V, V_{DS} = \text{Max Rating}$
		-	-	100		$V_{DS} = 0.8 \text{ Max Rating}, V_{GS} = 0V, T_A = 125^\circ\text{C}$
$I_{D(ON)}$	On-state drain current	0.5	1.0	-	A	$V_{GS} = 5.0V, V_{DS} = 25V$
		2.0	2.5	-		$V_{GS} = 10V, V_{DS} = 25V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	3.0	5.0	$\Omega$	$V_{GS} = 5.0V, I_D = 250mA$
		-	2.5	3.0		$V_{GS} = 10V, I_D = 1.0A$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	0.70	1.0	%/ $^\circ\text{C}$	$V_{GS} = 10V, I_D = 1.0A$
$G_{FS}$	Forward transconductance	300	450	-	mmho	$V_{DS} = 25V, I_D = 500mA$
$C_{ISS}$	Input capacitance	-	55	65	pF	$V_{GS} = 0V,$ $V_{DS} = 25V,$ $f = 1.0MHz$
$C_{OSS}$	Common source output capacitance	-	20	25		
$C_{RSS}$	Reverse transfer capacitance	-	5.0	8.0		
$t_{d(ON)}$	Turn-on delay time	-	3.0	5.0	ns	$V_{DD} = 25V,$ $I_D = 1.0A,$ $R_{GEN} = 25\Omega$
$t_r$	Rise time	-	5.0	8.0		
$t_{d(OFF)}$	Turn-off delay time	-	6.0	9.0		
$t_f$	Fall time	-	5.0	8.0		
$V_{SD}$	Diode forward voltage drop	-	1.2	1.8	V	$V_{GS} = 0V, I_{SD} = 1.0A$
$t_{rr}$	Reverse recovery time	-	400	-	ns	$V_{GS} = 0V, I_{SD} = 1.0A$

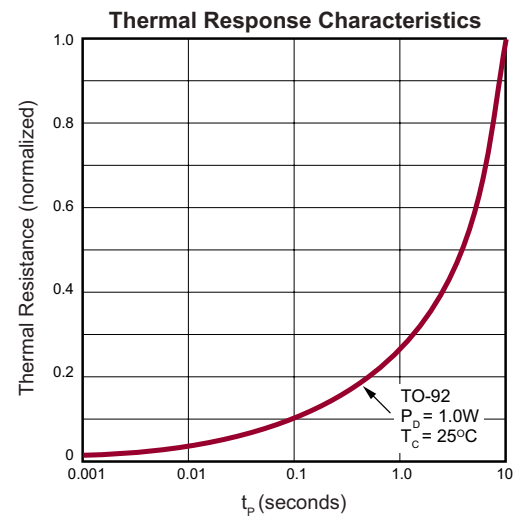
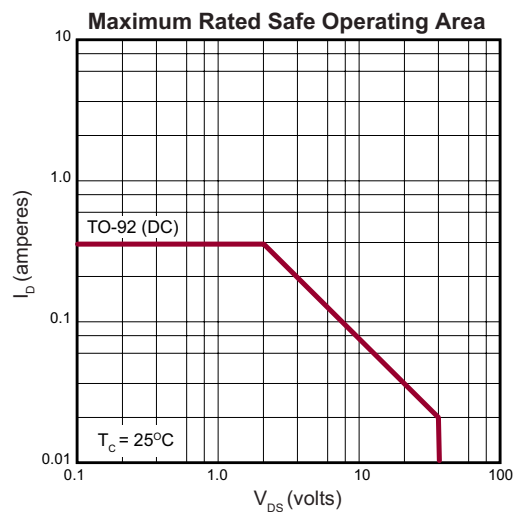
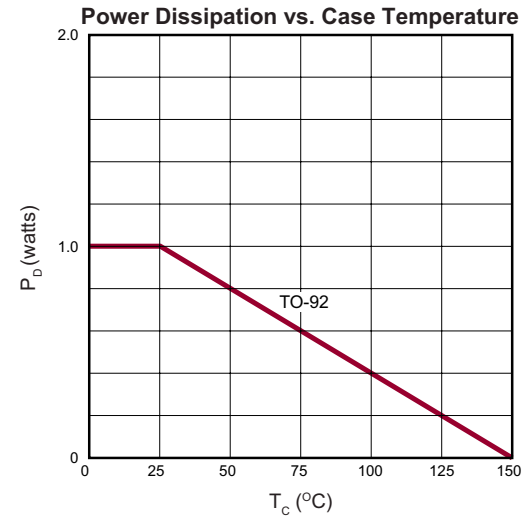
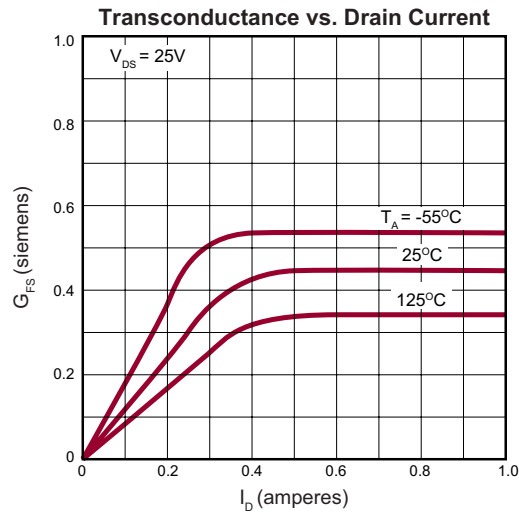
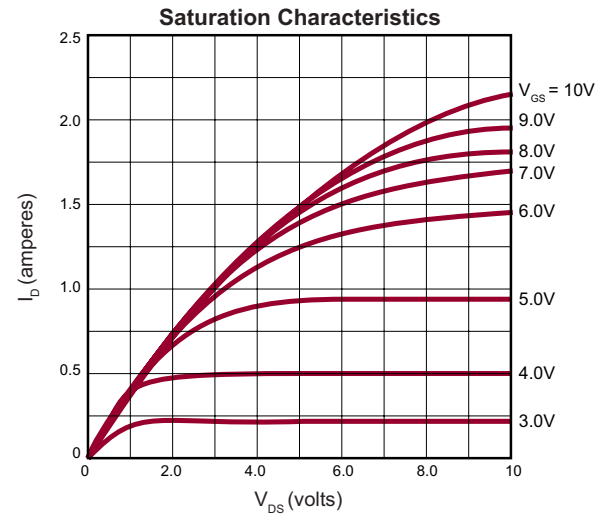
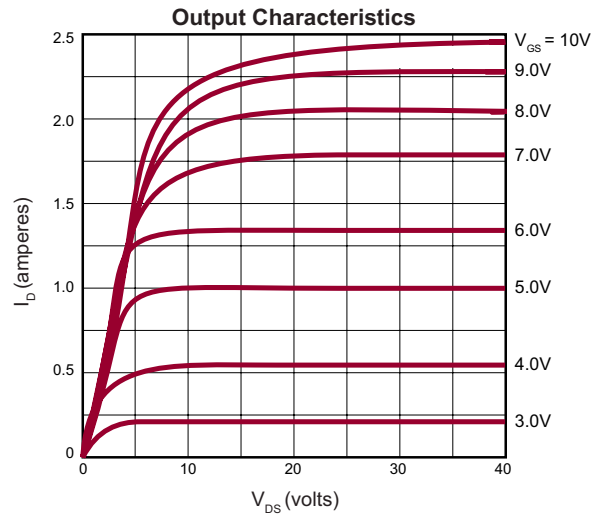
### Notes:

1. All D.C. parameters 100% tested at  $25^\circ\text{C}$  unless otherwise stated. (Pulse test: 300 $\mu\text{s}$  pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

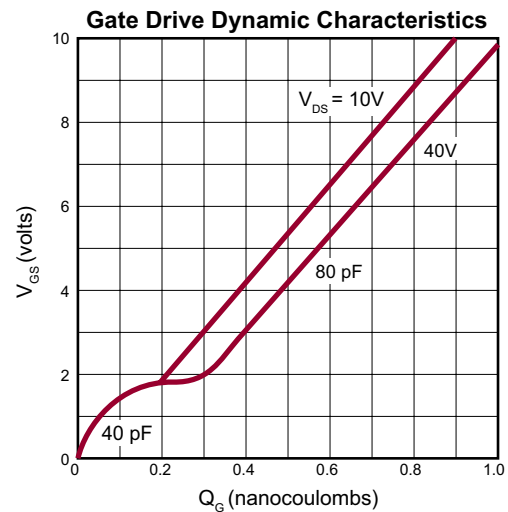
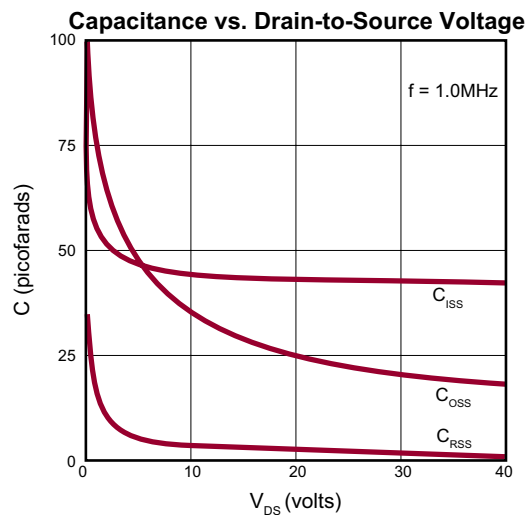
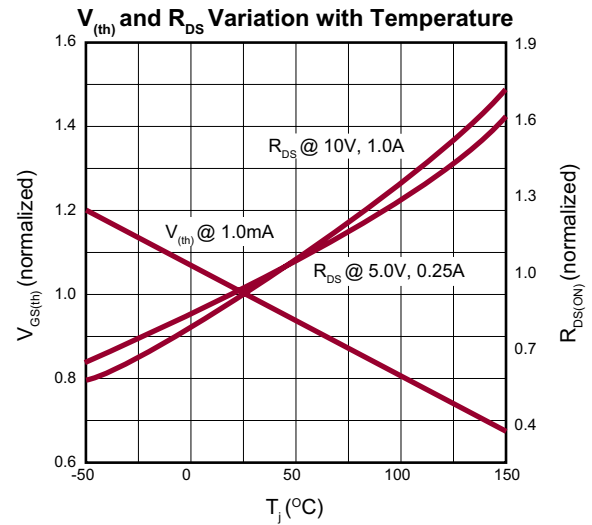
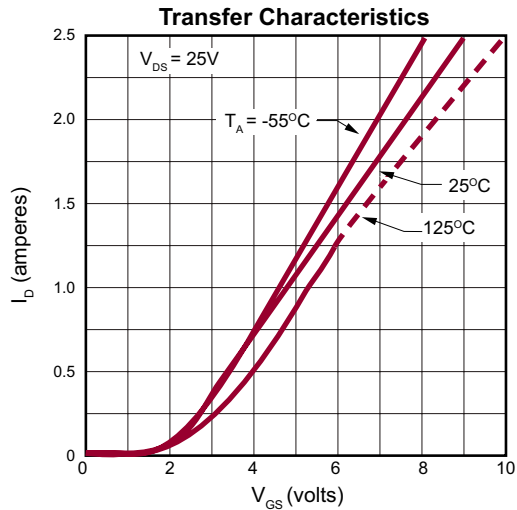
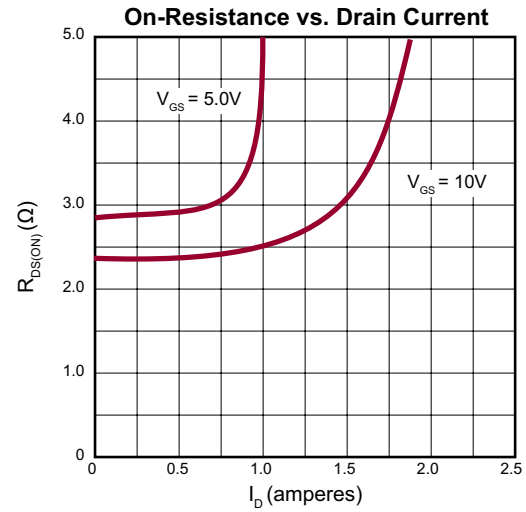
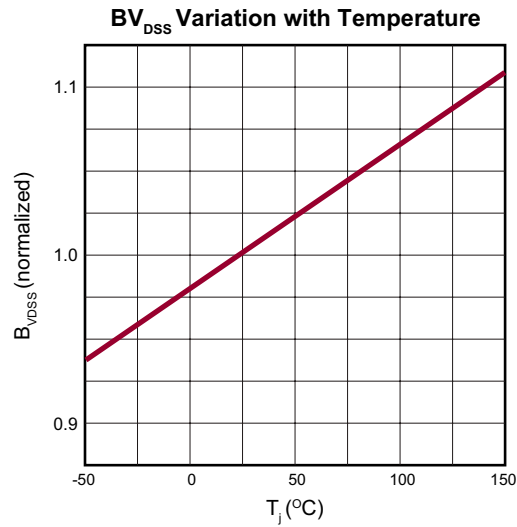
## Switching Waveforms and Test Circuit



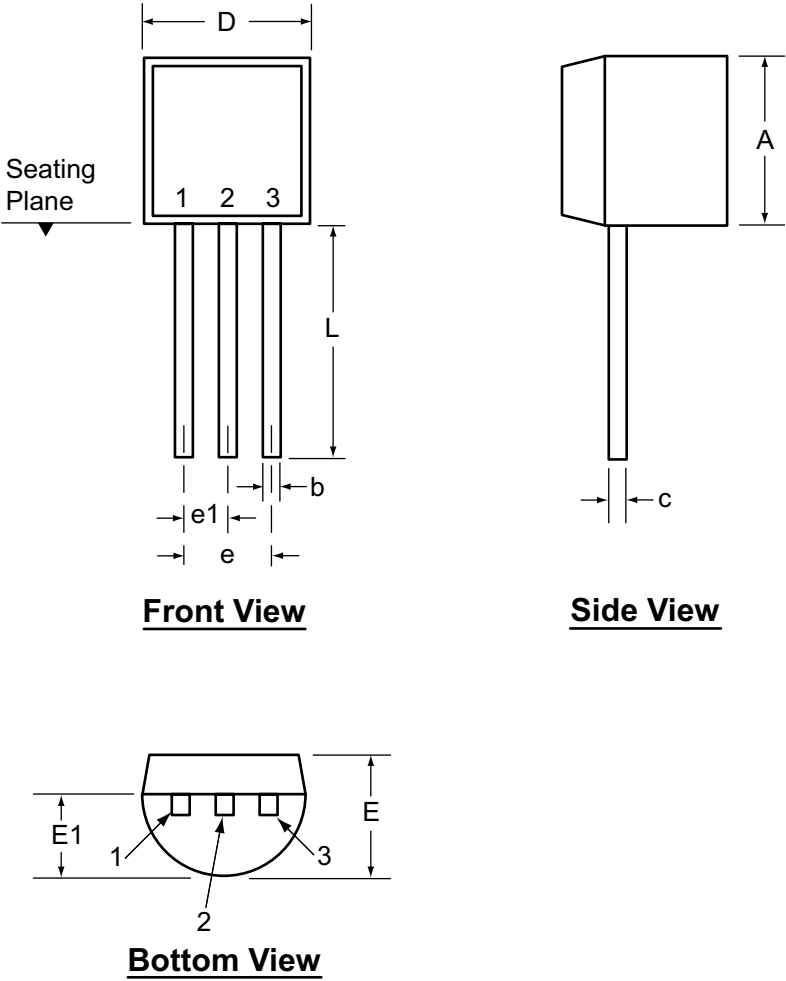
## Typical Performance Curves



## Typical Performance Curves (cont.)



3-Lead TO-92 Package Outline (N3)



Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.  
\* This dimension is not specified in the JEDEC drawing.  
† This dimension differs from the JEDEC drawing.  
**Drawings not to scale.**  
**Supertex Doc.#:** DSPD-3TO92N3, Version E041009.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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[VN0104N3](#) [VN0104N3-P013-G](#) [VN0104N3-P002-G](#) [VN0104N3-P003-G](#) [VN0104N3-G P002](#) [VN0104N3-G P013](#)  
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## P-Channel Enhancement-Mode Vertical DMOS FETs

### Features

- ▶ Free from secondary breakdown
- ▶ Low power drive requirement
- ▶ Ease of paralleling
- ▶ Low  $C_{iss}$  and fast switching speeds
- ▶ High input impedance and high gain
- ▶ Excellent thermal stability
- ▶ Integral source-to-drain diode

### Applications

- ▶ Motor controls
- ▶ Converters
- ▶ Amplifiers
- ▶ Switches
- ▶ Power supply circuits
- ▶ Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

### General Description

The Supertex VP0104 is an enhancement-mode (normally-off) transistor that utilizes a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors, and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

### Ordering Information

Device	Package	Wafer / Die Options		
	TO-92	NW (Die in wafer form)	NJ (Die on adhesive tape)	ND (Die in wafer pack)
VP0104	VP0104N3-G	VP1504NW	VP1504NJ	VP1504ND

For packaged products, -G indicates package is RoHS compliant ('Green'). Devices in Wafer / Die form are RoHS compliant ('Green'). Refer to Die Specification VF15 for layout and dimensions.

### Product Summary

Device	$BV_{DSS}/BV_{DGS}$ (V)	$R_{DS(ON)}$ (max) ( $\Omega$ )	$I_{D(ON)}$ (min) (mA)
VP0104N3-G	-40	8.0	-500

### Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	$BV_{DSS}$
Drain-to-gate voltage	$BV_{DGS}$
Gate-to-source voltage	$\pm 20V$
Operating and storage temperature	-55°C to +150°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

### Pin Configuration



### Product Marking



YY = Year Sealed  
WW = Week Sealed  
— = "Green" Packaging

Package may or may not include the following marks: Si or 

TO-92 (N3)

## Thermal Characteristics

Package	$I_D$ (continuous) <sup>†</sup> (mA)	$I_D$ (pulsed) (mA)	Power Dissipation @ $T_c = 25^\circ\text{C}$ (W)	$\theta_{jc}$ ( $^\circ\text{C}/\text{W}$ )	$\theta_{ja}$ ( $^\circ\text{C}/\text{W}$ )	$I_{DR}^{\dagger}$ (mA)	$I_{DRM}$ (mA)
TO-92	-250	-800	1.0	125	170	-250	-800

### Notes:

<sup>†</sup>  $I_D$  (continuous) is limited by max rated  $T_j$ .

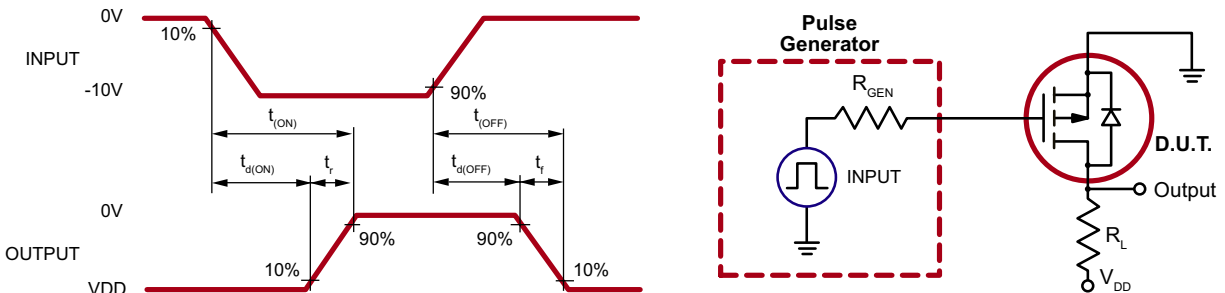
## Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter	Min	Typ	Max	Units	Conditions
$BV_{DSS}$	Drain-to-source breakdown voltage	-40	-	-	V	$V_{GS} = 0V, I_D = -1.0mA$
$V_{GS(th)}$	Gate threshold voltage	-1.5	-	-3.5	V	$V_{GS} = V_{DS}, I_D = -1.0mA$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	5.8	6.5	mV/ $^\circ\text{C}$	$V_{GS} = V_{DS}, I_D = -1.0mA$
$I_{GSS}$	Gate body leakage current	-	-1.0	-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
$I_{DSS}$	Zero gate voltage drain current	-	-	-10	$\mu\text{A}$	$V_{GS} = 0V, V_{DS} = \text{Max Rating}$
		-	-	-1.0	mA	$V_{DS} = 0.8 \text{ Max Rating}, V_{GS} = 0V, T_A = 125^\circ\text{C}$
$I_{D(ON)}$	On-state drain current	-0.15	-0.25	-	A	$V_{GS} = -5.0V, V_{DS} = -25V$
		-0.5	-1.2	-		$V_{GS} = -10V, V_{DS} = -25V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	-	11	15	$\Omega$	$V_{GS} = -5.0V, I_D = -100mA$
		-	6.0	8.0		$V_{GS} = -10V, I_D = -500mA$
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature	-	0.55	1.0	%/ $^\circ\text{C}$	$V_{GS} = -10V, I_D = -500mA$
$G_{FS}$	Forward transconductance	150	190	-	mmho	$V_{DS} = -25V, I_D = -500mA$
$C_{ISS}$	Input capacitance	-	45	60	pF	$V_{GS} = 0V,$ $V_{DS} = -25V,$ $f = 1.0MHz$
$C_{OSS}$	Common source output capacitance	-	22	30		
$C_{RSS}$	Reverse transfer capacitance	-	3.0	8.0		
$t_{d(ON)}$	Turn-on delay time	-	4.0	6.0	ns	$V_{DD} = -25V,$ $I_D = -500mA,$ $R_{GEN} = 25\Omega$
$t_r$	Rise time	-	3.0	10		
$t_{d(OFF)}$	Turn-off delay time	-	8.0	12		
$t_f$	Fall time	-	4.0	10		
$V_{SD}$	Diode forward voltage drop	-	-1.2	-2.0	V	$V_{GS} = 0V, I_{SD} = -1.0A$
$t_{rr}$	Reverse recovery time	-	400	-	ns	$V_{GS} = 0V, I_{SD} = -1.0A$

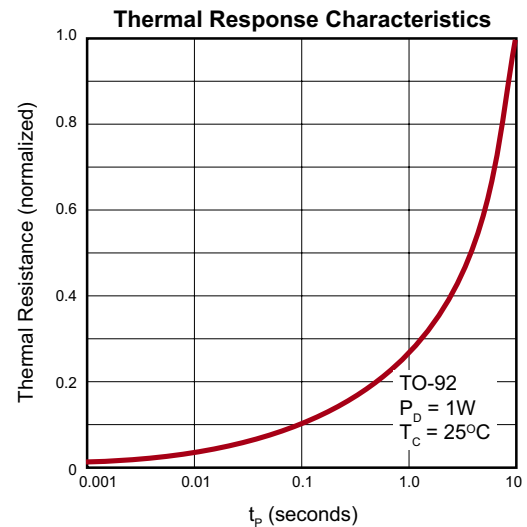
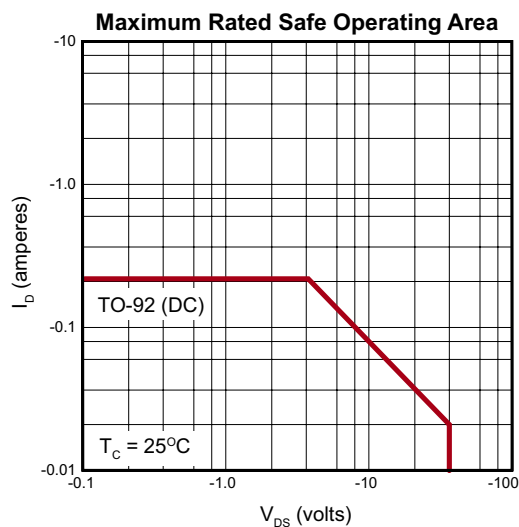
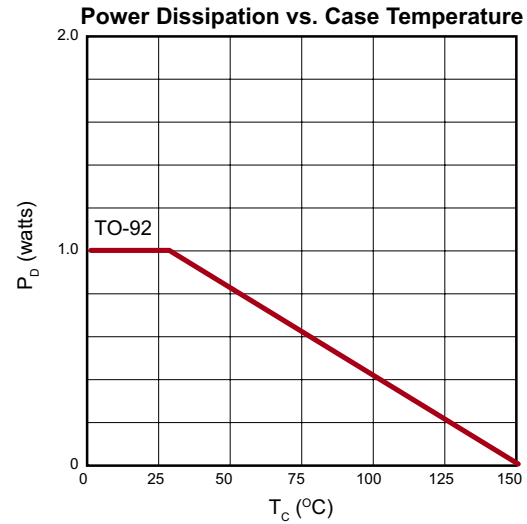
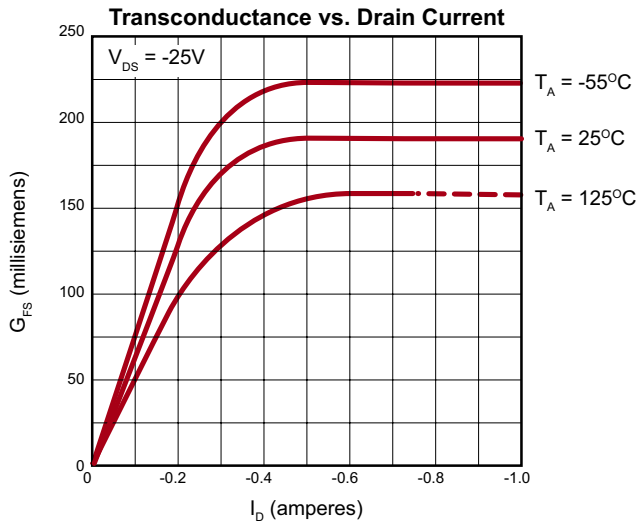
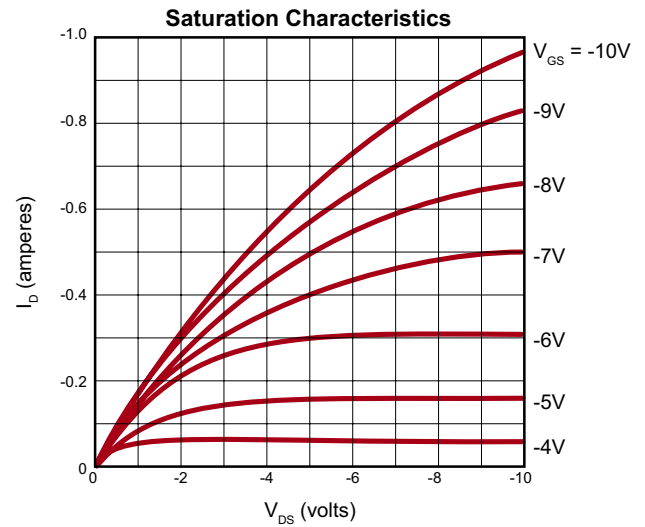
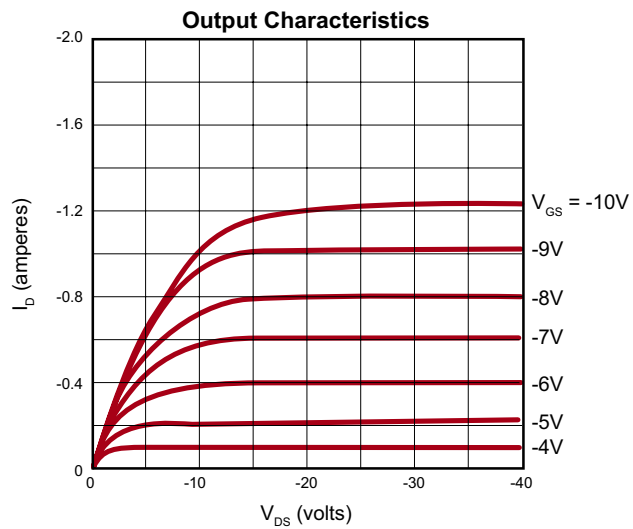
### Notes:

1. All D.C. parameters 100% tested at  $25^\circ\text{C}$  unless otherwise stated. (Pulse test:  $300\mu\text{s}$  pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

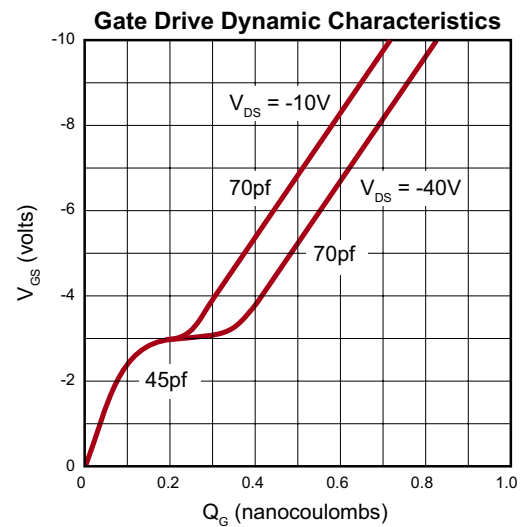
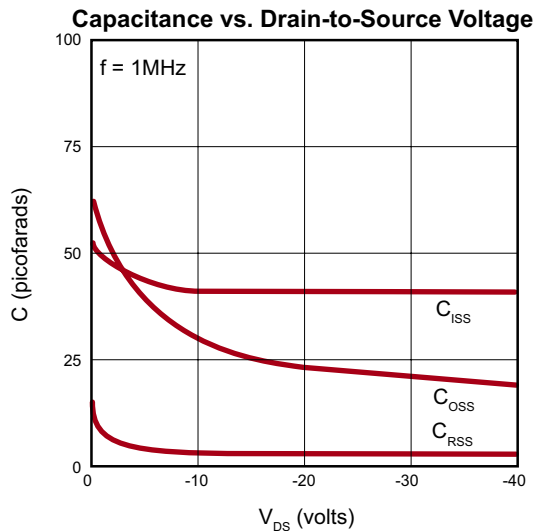
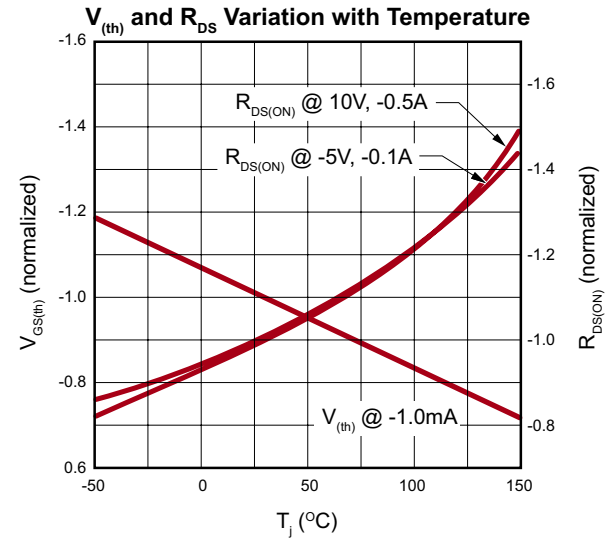
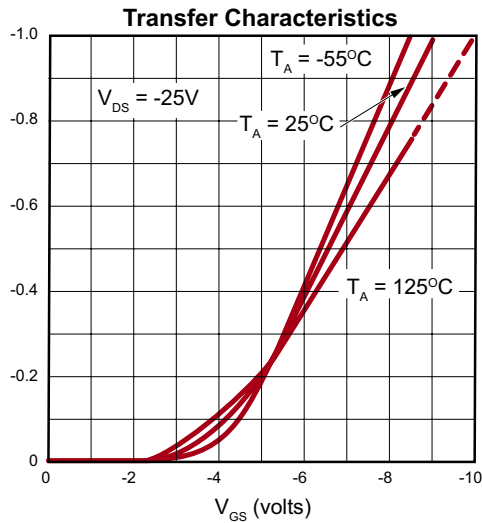
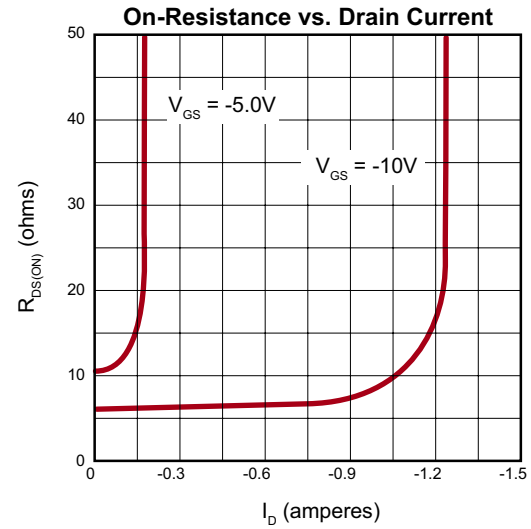
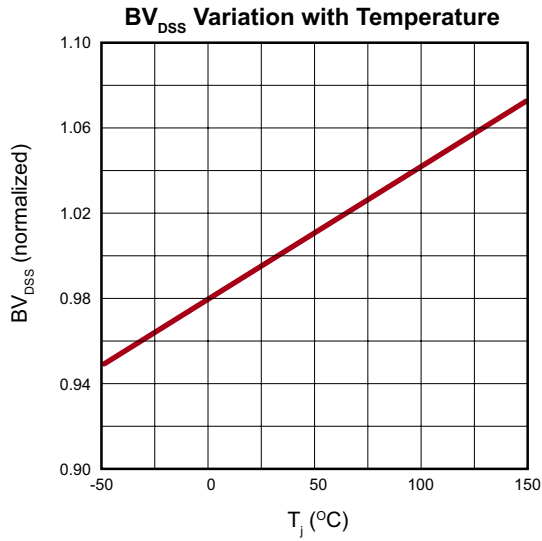
## Switching Waveforms and Test Circuit



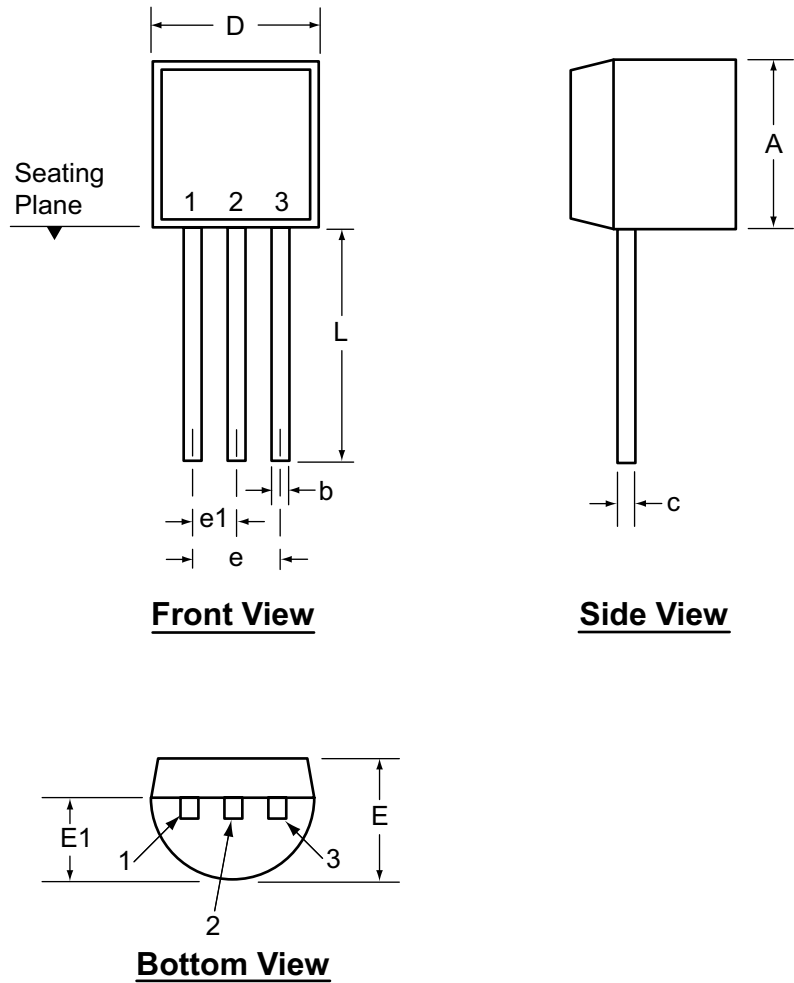
## Typical Performance Curves



## Typical Performance Curves (cont.)



# 3-Lead TO-92 Package Outline (N3)



Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.  
 \* This dimension is not specified in the JEDEC drawing.  
 † This dimension differs from the JEDEC drawing.  
**Drawings not to scale.**  
**Supertex Doc.#:** DSPD-3TO92N3, Version E041009.

(The package drawing (s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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